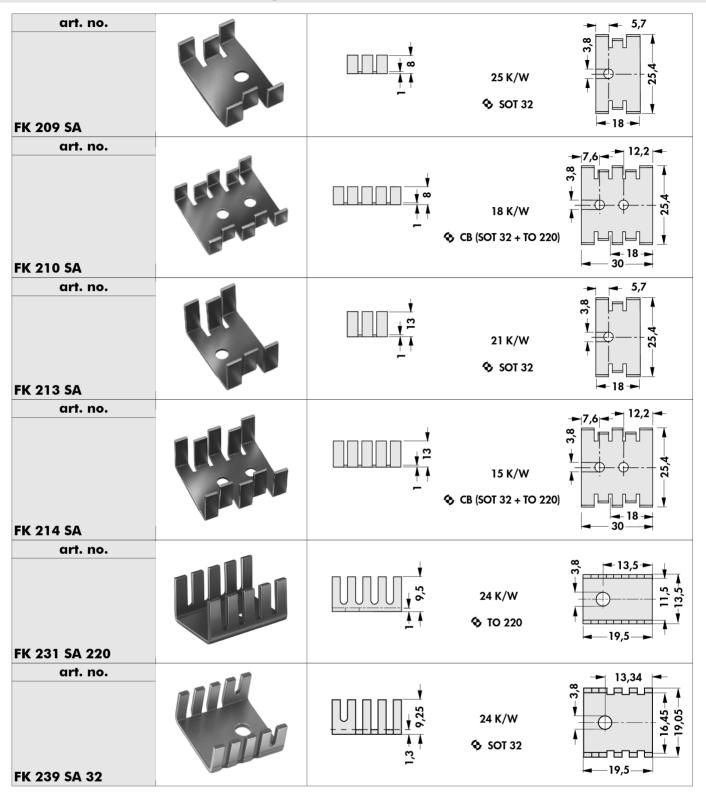
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Heatsinks for transistors in plastic case



The heatsinks FK 209 \dots 214 are available without hole pattern as well, e.g. FK 209 SA

material: aluminium surface treatment: black anodised

Retaining springs for transistors Heatsinks for D PAK GEL thermal conductive foil Insulator caps → A 111 - 116 → C 17 → E 7 → E 40 Mounting material for semiconduct. \rightarrow E 34 – 38 Mounting pads \rightarrow E 36 Mounting pads for transistors \rightarrow E 37 Mounting parts for heatsinks \rightarrow E 39 – 40

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